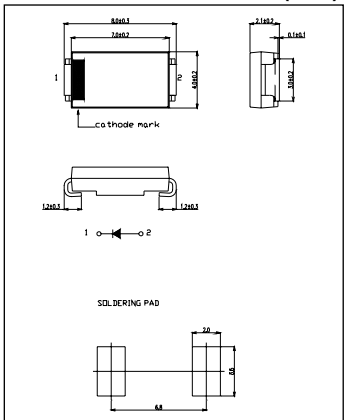
3A Avg. 200 Volts Standard Recovery Diode NSD03A20

■最大定格 Maximum Ratings

Item	Symbol	Conditions			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	200			V
平均整流電流 Average Rectified Output Current	I_O	50Hz 正弦半波抵抗負荷 50Hz half sine wave Resistance load	Ta＝25℃*1	1.57	A
			Tl＝108℃*2	3.0	A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	4.71			A
サージ順電流 Surge Forward Current	I_{FSM}	80 50Hz正弦半波，1サイクル，非くり返し 50Hz Half Sine Wave,1cycle, Non-repetitive			A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	−40～＋150			℃
保存温度範囲 Storage Temperature Range	T_{stg}	−40～＋150			℃

■OUTLINE DRAWING(mm)



■Approx Net Weight:0.16g

■電気的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	T_j＝25℃, V_{RM}＝V_{RRM}	−	−	50	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	T_j＝25℃, I_{FM}＝3A	−	−	1.0	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間*1 Junction to Ambient	−	−	89	℃/W
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	−	−	13	℃/W

＊1：アルミナ基板実装 /Alumina Substrate mounted (Soidering Lands= 2 × 3.5 mm , Both Sides)
＊2：Tl：リード温度/Tl：Lead Temperature

■定格・特性曲線

FIG.1
順電圧特性
FORWARD CURRENT VS. VOLTAGE

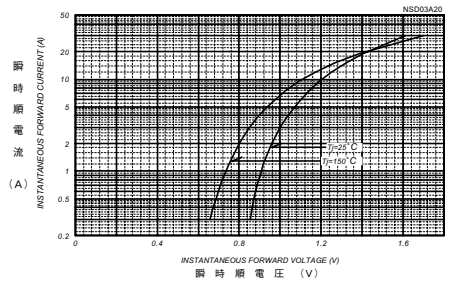


FIG.2
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

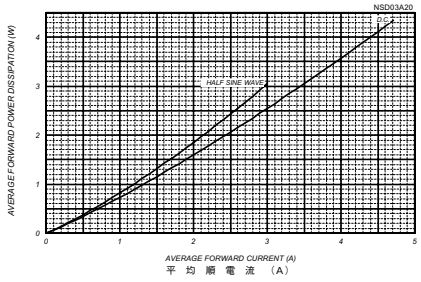


FIG.3
平均順電流－周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Alumina Substrate Mounted(Soldering Land=2*3.5mm)

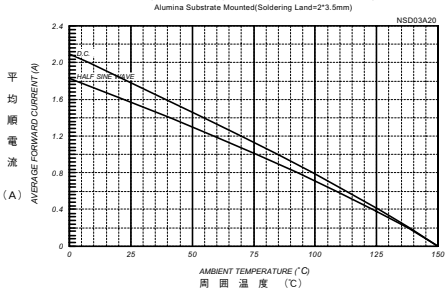


FIG.4
平均順電流－周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE
Glass-Epoxy Substrate Mounted(Soldering Land=2*3.5mm)

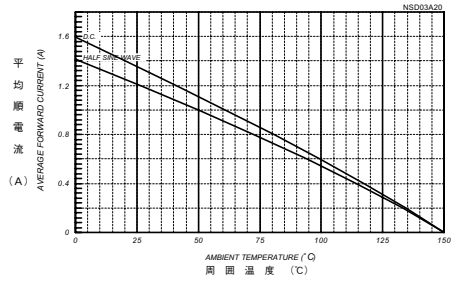


FIG.5
平均順電流－リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

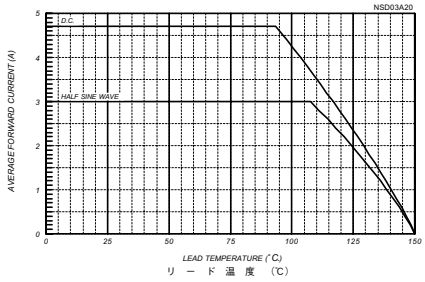
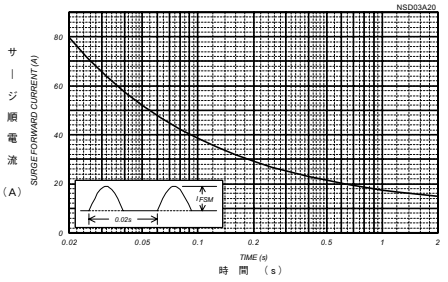



FIG.3
サージ順電流定格
SURGE CURRENT RATINGS
f=50Hz,Half Sine Wave,Non-Repetitive,No Load